

Bectronic Industries Alliance PINS: (010CT2004)

1. Project Nu	mber Assigned by EIA:		PN 5099		
2. Final Publis	shed Document Number Assigned:		EIA-198-E Section III/3		
3. Title of Fina	al Published Document:	SM	SMD Multilayer Ceramic Chip Capacitors		
4. Project Intent: (Check the applicable box(s) below)					
	Create a New Document		Modify Existing Document		
	EIA Component Bulletin		Revise current published document		
	EIA standard	\boxtimes	Revise and Redesignate current published document		
	Joint Industry Document		Revise, Redesignate and Consolidate current document		
Crea	ate new American National Standard (ANSI)	\square	Revise and Partition current document		
Conduct Survey			Reaffirm current document		
	Other (Please explain)		Reaffirm and Redesignate current document		
			Supplement to a current document		
			Withdraw current document		
5. Estimated	Project Completion Date (mmm yy):		Convert to Historical Document designation		
	Sep	05	Other (Please explain)		
6. Description	n of Contents of Document: (Provide a on	e para	agraph description, not to exceed 500 characters.)		
These fixed value SMD chip capacitors are unencapsulated, multilayer ceramic dielectric components with solderable end terminations.					
7. Units of Me	asurement Used: (check applicable boxes)		Metric 🛛 US 🗌 Non-Measurement Sensitive		
8. Formulating Body (Organization, Committee/Subcommittee Title and Acronym):		P-2.1			
			Leader: (Specify name and complete contact information, address, ct will be Formulating Group Chair as completed in 9. below.)		
Name:	Michael Cannon		Phone:		
Organization:	TDK Corporation		Fax:		
Address:	1221 Business Center		Email:		
City, ST, Zip:	Mt. Prospect, IL 60056				
10. Formulati	ng Group Chair: (Specify name and comple	ete con	ntact information, address, phone, email, etc.)		
Name:	same as above		Phone:		
Organization:			Fax:		
Address:			Email:		
City, ST, Zip:					